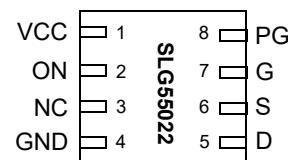
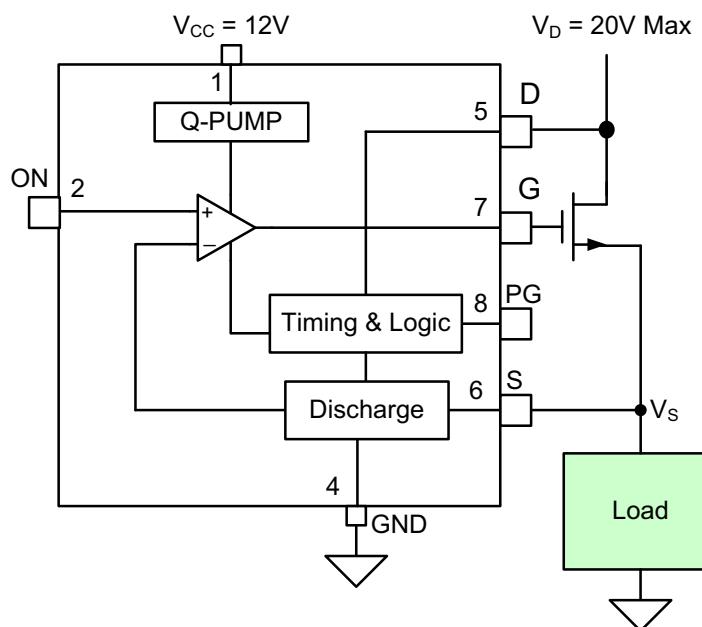


**Features**

- 12 V Power supply
- Drain Voltage Range 1.0 V to 20 V
- Internal Gate Voltage Charge Pump
- Controlled Turn on Delay
- Controlled Load Discharge Rate
- Controlled Turn on Slew Rate
- 2mm x 2mm TDFN-8 Package
- Pb-Free / Halogen-Free / RoHS compliant

**Pin Configuration****8-pin TDFN  
(Top View)****Applications**

- Power Rail Switches
- Hot Plugging Applications
- Soft Switching
- Personal computers and Servers
- Data Communications Equipment

**Block Diagram**

**Pin Description**

Pin #	Pin Name	Type	Pin Description
VCC	1	Power	Supply Voltage
ON	2	Input	CMOS Logic Level. High True
NC	3	--	No Connect.
GND	4	GND	Ground.
D	5	Input	FET Drain Connection
S	6	Input	Source Connection
G	7	Output	FET Gate Drive
PG	8	Output	Output CMOS Open Drain - Power Good, indicates external FET fully on. Pull-up resistor greater than 300 kΩ recommended.

**Overview**

The SLG55022 N-Channel FET Gate Driver is used for controlling a delayed turn on and ramping slew rate of the source voltage on N-Channel FET switches from a CMOS logic level input. Intended as a supporting control element for switched voltage rails in energy efficient, advanced power management systems, the SLG55022 also integrates circuits to discharge opened switched voltage rails. The gate driver is available in a variety of configurations supporting a range of turn-on slew rates from 0.80 V/ms up to 4 V/ms which, depending on load supplying source voltages in the range of 1.0 V to 20 V results in ramp times from 200µs to over 20 ms (see Application Section). Delays until the ramp begins are source voltage independent and range from 250µs to 5ms. A power good condition is output to indicate that the ramp-up slew of the source voltage is finished. Additionally, an internal discharge circuit provides a controlled path to remove charge from open power rails. The SLG55022 gate drive is packaged in an 8 pin DFN package.

When used with external N-Channel FETs, the SLG55022 supports low transient, energy efficient switching of high current loads at source voltages ranging from 1.0V to 20V.

**Ordering Information**

Part Number	Type
SLG55022-200030V	TDFN-8
SLG55022-200030VTR	TDFN-8 - Tape and Reel (3k units)

## Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
$V_D$ or $V_S$ to GND	-0.3	40.0	V
Voltage at Logic Input pins	-0.3	6.5	V
Current at input pin	-1.0	1.0	mA
Storage temperature range	-65	150	°C
Junction temperature	--	150	°C
ESD Human Body Model	--	2000	V
ESD Machine Model	--	200	V
Moisture Sensitivity Level	1		

## Electrical Characteristics

 $T_A = -10$  °C to 75 °C

Parameter	Description	Conditions	Min.	Typ.	Max.	Unit
$V_{CC}$	Supply Voltage		11.5	12.0	12.5	V
$T_{VCC\_RAMP}$	$V_{CC}$ Ramp-up Rate	See Note 1	0.25	--	--	V/ms
$I_q$	Quiescent Current	$V_G$ not ramping FET = ON		50	80	µA
		$V_G$ not ramping FET = OFF		0.1	1	µA
$V_D$	FET Drain Voltage		1.0	--	21	V
$V_{GS}$	Gate-Source Voltage		8.0	11.5	16	V
$C_G$	FET Gate Capacitance		500	--	8000	pF
$T_{DELAY}$	Ramp Delay Range	1.5ms Default, 500µs step	0	500	750	µs
$T_{SLEW}$	FET Turn on Slew Rate		1.2	2.0	2.8	V/ms
$I_{DISCHARGE}$	Internal Discharge Resistor	Nominal discharge time of ~100ms 10mA max rate	180	300	420	Ω
$V_{IH}$	HIGH-level input voltage	ON (200mV Hysteresis)	2.4	--	5.5	V
$V_{IL}$	LOW-level Input voltage	ON (200mV Hysteresis)	--	--	0.4	V
$V_{OH}$	HIGH-level output voltage	PG Open Drain	--	--	5.5	V
$I_{OL\_LOGIC}$	Logic LOW level output	PG Sink Current	1	2	3	mA
$I_{IH}^*$	HIGH-level input current	$V_{IH} = 3.3V$	--	--	<1.0	µA

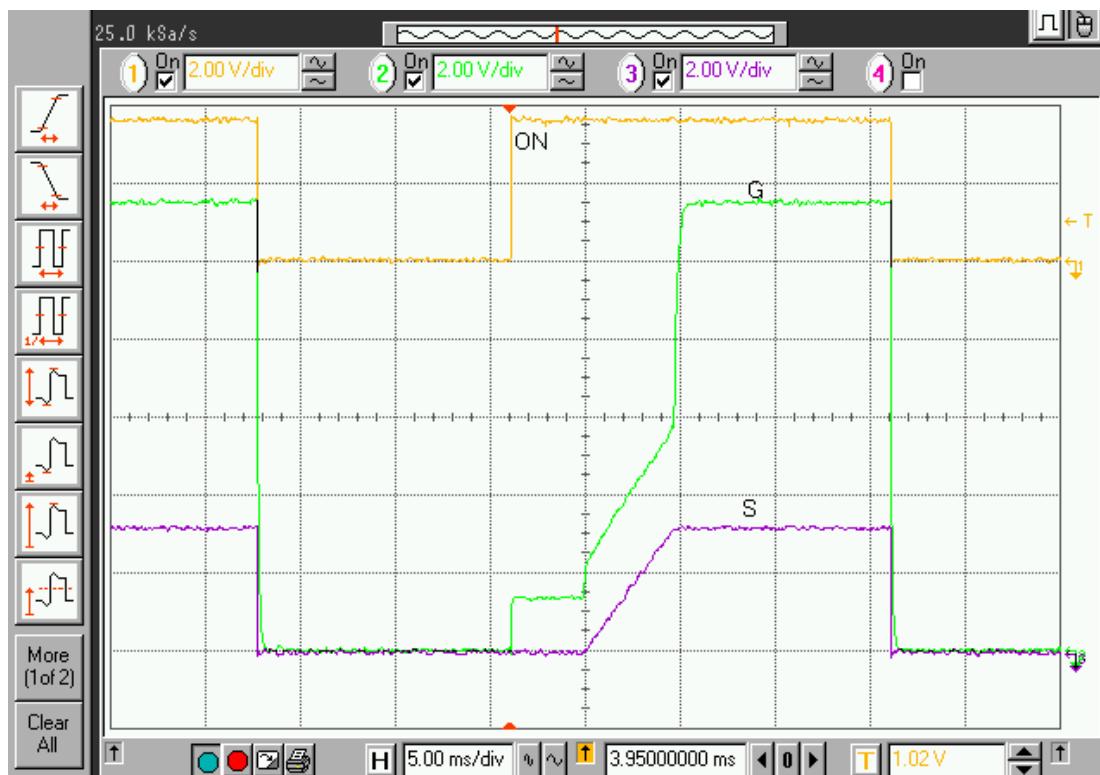
## Notes:

1. If  $T_{VCC\_RAMP} > 5V/ms$  and ON is asserted, Gate charging will begin after 1ms.

## Device Operation

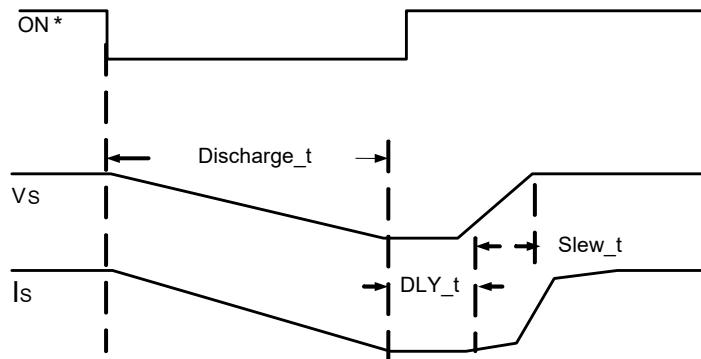
In a typical application, de-asserting ON (low) turns off the external power N-FET. When the FET is turned off, the voltage at the load is discharged through a resistor (300 Ohms) internal to the SLG55022. When ON is asserted (high), the device will not begin driving the gate of the external power FET unless the voltage at the drain of the device is at or above 0.8 V (e.g.  $V_D \geq 0.8$  V) to prevent a 'shootthrough' situation to the FET's source load. Gate voltage is not applied to the gate of the external power N-FET after  $DLY_t$  then the gate source ( $V_{gs}$ ) voltage is ramped up to 11.5V above the source voltage  $V_S$  at a slew rate determined by the internal slew rate control element internal to the SLG55022. Monotonic rise of  $V_S$  is maintained even as  $ID$  increases dramatically after the load device turn on threshold voltage is reached. After the source voltage has ramped up to its maximum steady state value, the Open Drain PG (Power Good) signal is asserted. PG may be used as the ON control of a second SLG55022 thereby providing power on sequence control of a number of switched power rails, or used in a 'wired and' with other PG signals to indicate all switched power rails are in a power good condition.

The waveforms shown illustrate the monotonic rise of the source voltage of a FET as gate voltage is controlled to accommodate for variations in load current as the voltage is applied.



### Delay Time and Slew Rates

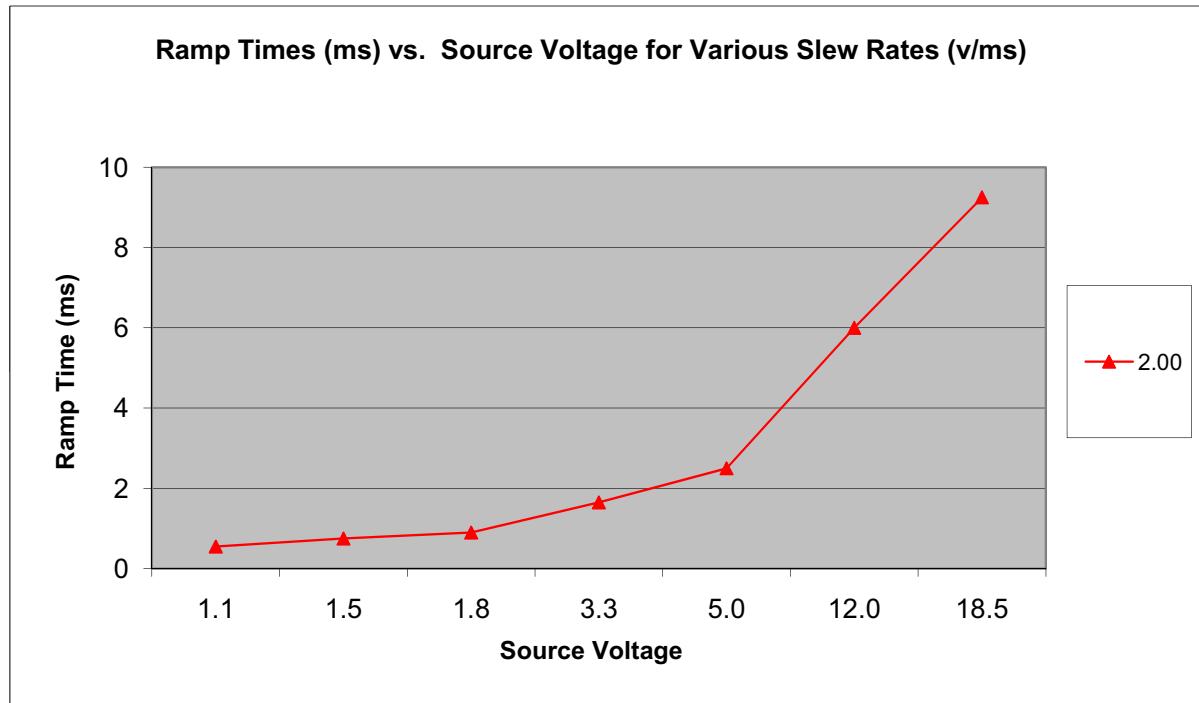
The two components of controlling the application of FET source voltage to the load are a fixed time delay before beginning turn on of the FET (DLY\_t below) and the Slew Time of the source voltage (Slew\_t below).



Having control over the Slew Rate of the FET's source voltage as the FET is turning on is important in controlling  $dv/dt$  caused transients. A power FET, for example, switching a 5 V rail which has a total of 500  $\mu$ F of decoupling, fully on in 10  $\mu$ s will generate a 250 A current surge which is very undesirable. If the FET turn on time can be stretched to 1 ms, the current surge to charge the decoupling capacitors is reduced to 2.5 A. The SLG55022 controls slew rate of a FET's source voltage as it is turned on. A range of slew rates are available as device order options. Obviously the time to fully slew the source voltage to fully on is a function of the drain supply voltage. The table and graph below shows source voltage ramp times for various slew rates supported by the SLG55022 for a range of specific source voltages.

Slew Rates (V/ms)	Ramp Times (ms) vs. Source Voltages (V)						
	1.1 V	1.5 V	1.8 V	3.3 V	5.0 V	12 V	18.5 V
2.00	0.55	0.75	0.90	1.65	2.50	6.00	9.25

\* The minimum time that ON can be de-asserted between switching cycles is 100 ms.



**Package Top Marking System Definition  
For devices manufactured after 2021**

PPP	Part Code
NNN	Serial Number
R	Pin 1 Identifier + Revision Code

PPP - Part Code Field: Identifies the specific device Configuration

NNN - Serial Number Field: Serial number

R - Revision Code Field: Device Revision

**For devices manufactured before 2021**

XXA	Part ID + Assembly Code
DDL	Date Code + Lot
R	Pin 1 Identifier + Revision Code

XX - Part ID Field: Identifies the specific device Configuration

A - Assembly Code Field: Assembly Location of the device

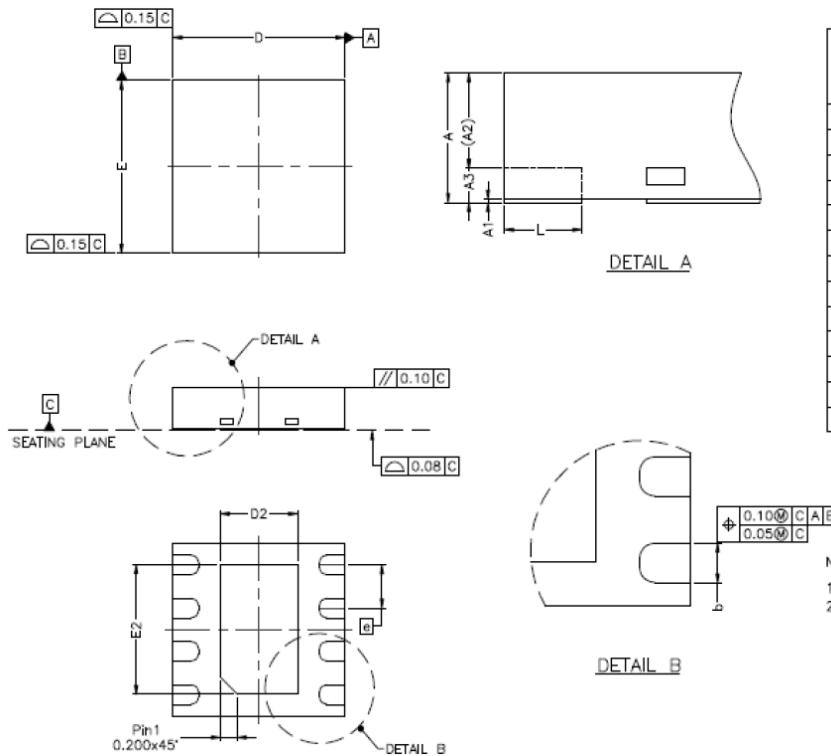
DD - Date Code Field: Coded Date of Manufacture

L - Lot Code: Designates Lot #

R - Revision Code: Device Revision

## Package Drawing and Dimensions

## 8 Lead TDFN Package



SYMBOL	DIMENSION (MM)			DIMENSION (MIL)		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	28	30	31
A1	0.00	0.02	0.05	0	1	2
A2	0	0.55	0.80	0	22	31
A3	—	0.20	—	—	8	—
b	0.18	0.25	0.30	7	10	12
D	1.90	2.00	2.10	74	79	83
D1	—	—	—	—	—	—
D2	0.75	0.90	1.05	30	35	41
E	1.90	2.00	2.10	75	79	83
E1	—	—	—	—	—	—
E2	1.50	1.65	1.70	53	59	65
e	0.50 BSC			20 BSC		
L	0.25	0.30	0.35	10	12	14

## NOTE :

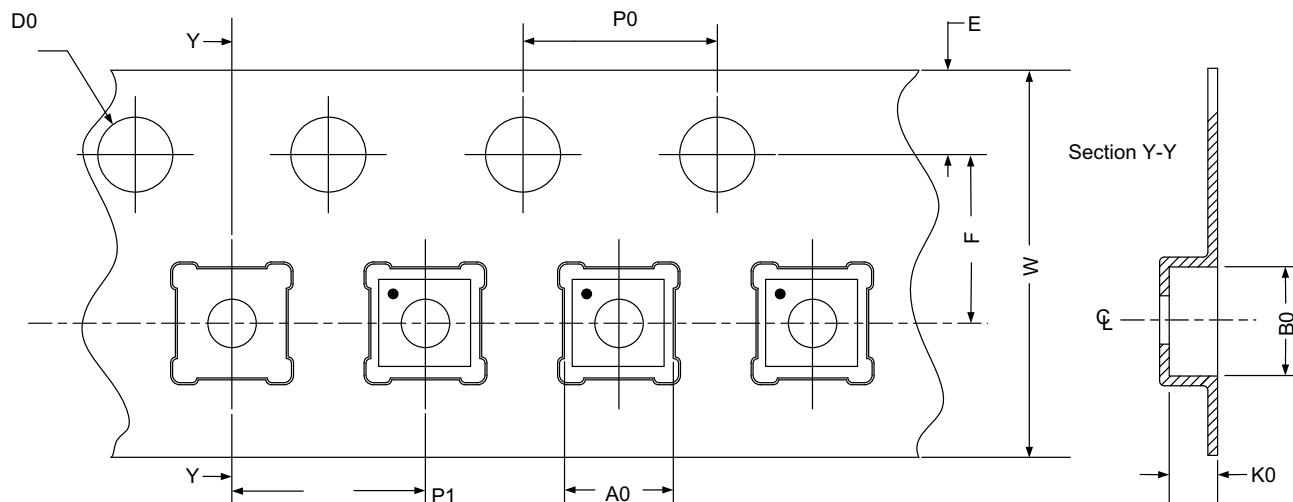
1. REFER TO JEDEC STD: MO-229.
2. DIMENSION "b" APPLIES TO METALLIZED TERMINAL AND IS MEASURED BETWEEN 0.15MM AND 0.30MM FROM THE TERMINAL TIP. IF THE TERMINAL HAS OPTIONAL RADIUS ON THE OTHER END OF THE TERMINAL, THE DIMENSION B SHOULD NOT BE MEASURED IN THAT RADIUS AREA.

## Tape and Reel Specifications

Package Type	# of Pins	Nominal Package Size [mm]	Max Units		Reel & Hub Size [mm]	Leader (min)		Trailer (min)		Tape Width [mm]	Part Pitch [mm]
			per Reel	per Box		Pockets	Length [mm]	Pockets	Length [mm]		
TDFN 8L Green	8	2 x 2 x 0.75	3,000	3,000	178 / 60	100	400	100	400	8	4

## Carrier Tape Drawing and Dimensions

Package Type	Pocket BTM Length	Pocket BTM Width	Pocket Depth	Index Hole Pitch	Pocket Pitch	Index Hole Diameter	Index Hole to Tape Edge	Index Hole to Pocket Center	Tape Width
	A0	B0	K0	P0	P1	D0	E	F	W
TDFN 8L Green	2.3	2.3	1.05	4	4	1.55	1.75	3.5	8



## Recommended Reflow Soldering Profile

Please see IPC/JEDEC J-STD-020: latest revision for reflow profile based on package volume of 3.00 mm<sup>3</sup> (nominal). More information can be found at [www.jedec.org](http://www.jedec.org).

## Revision History

Date	Version	Change
6/8/2023	1.05	Updated Part Marking Definition
2/9/2022	1.04	Updated Company name and logo Fixed typos
7/10/2018	1.03	Updated style and formatting
7/29/2017	1.02	Added Pb-Free/Halogen Free/RoHS compliance Added MSL

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